

Rev. V1

#### **Features**

- 25 dB Gain
- 33 dBm Output IP3
- 24 dBm P1dB
- 25 dBm P3dB
- 5.5 V Drain Supply
- 4 mm, 24 lead AQFN Package
- RoHS\* Compliant

#### **Applications**

Ka-Band Communication

#### **Description**

The MAAP-011340 is a 1/4 W Ka-band amplifier. The amplifier has a 24 dBm typical P1dB and a 25 dBm typical P3dB with 25 dB of gain. The typical IP3 is 33 dBm. The drain bias supply is 5.5 V. The gate voltage is adjusted to set the drain current to 275 mA.

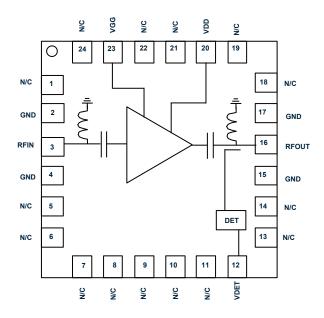
The MAAP-011340 is designed for Ka-band satellite communication applications. The 4 mm, 24 lead AQFN package is lead free and RoHS compliant.

## Ordering Information<sup>1</sup>

Part Number	Package
MAAP-011340-TR1000	1000 Piece Reel
MAAP-011340-TR3000	3000 Piece Reel
MAAP-011340-SMB	Sample Board

<sup>1.</sup> Reference Application Note M513 for reel size information.

## **Block Diagram**



## Pin Configuration<sup>2,3</sup>

Pin#	Pin Name	Description
1,5-11, 13, 14, 18, 19, 21, 22, 24	N/C	No Connect
2,4,15,17	GND	Ground
3	RFIN	RF Input
12	VDET	Detector Voltage
16	RFOUT	RF Output
20	VDD	Drain Voltage
23	VGG	Gate Voltage

- 2. It is recommended that all NC (No Connect) pins be grounded.
- 3. The exposed pad centered on the package bottom must be connected to RF, DC, and thermal ground.

<sup>\*</sup> Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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#### **Electrical Specifications:**

Freq. = 27.0 - 31.5 GHz,  $V_{DD}$  = +5.5 V,  $I_{DQ}$  = 275 mA,  $T_A$  = 25°C,  $Z_0$  = 50  $\Omega$ 

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Gain	_	dB	22	25	_
Gain Flatness	_	dB	_	± 0.7	_
Input Return Loss	_	dB	_	10	_
Output Return Loss	_	dB	_	10	_
P1dB	_	dBm	_	24	_
P3dB	_	dBm	_	25	_
P <sub>OUT</sub>	27 GHz, $P_{IN}$ = 4.0 dBm 31.5 GHz, $P_{IN}$ = 4.0 dBm	dBm	24.5 23.5	25.5 24.5	_
Output IP3	P <sub>OUT</sub> = 16 dBm per tone with 10 MHz spacing	dBm	_	33	_
Noise Figure	_	dB		6.1	_
$V_{DET}$	0 dBm Output Power 24 dBm Output Power	V	 1.4	0.6 1.8	 2.1
$V_{GG}$	Small Signal	V	_	-0.68	_
I <sub>GG</sub>	Small Signal P3dB	mA		-0.7 -0.8	
I <sub>DD</sub>	P1dB P3dB	mA	_	300 320	_

### Bias Sequence

All gate voltages must be applied prior to applying drain voltages.

- 1. Apply V<sub>GG</sub> (about -0.75 V) to pin 23.
- 2. Apply V<sub>DD</sub> (+5.5 V) to pin 20.
- Adjust V<sub>GG</sub> to set I<sub>DQ</sub> to 275 mA.

Shut down by removing V<sub>DD</sub> first.

## **Maximum Operating Conditions**

Parameter	Maximum
TX Input Power	+5 dBm
V <sub>DD</sub>	+6 V
V <sub>GG</sub>	-3 to 0 V
Junction Temperature <sup>4,5</sup>	+160°C
Operating Temperature	-40°C to +85°C

<sup>4.</sup> Operating at nominal conditions with  $T_J \le +160$ °C will ensure MTTF > 1 x  $10^6$  hours.

T<sub>J</sub> = 148.5°C @ 5.5 V, 275 mA

## **Static Sensitivity**

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 1C and CDM Class C2A devices.

## Absolute Maximum Ratings<sup>6,7</sup>

Parameter	Parameter Absolute Maximum	
TX Input Power	+8 dBm	
V <sub>DD</sub>	+6.5 V	
$V_{GG}$	-5 to 0 V	
Junction Temperature <sup>8</sup>	+175°C	
Storage Temperature	-65°C to +125°C	

<sup>6.</sup> Exceeding any one or combination of these limits may cause permanent damage to this device.

TX Junction Temp. (T<sub>J</sub>) = T<sub>C</sub> + Θjc \* ((V \* I) - (P<sub>OUT</sub> - P<sub>IN</sub>)). Typical TX thermal resistance (Θjc) = 42°C/W. a) For T<sub>C</sub> = +85°C,

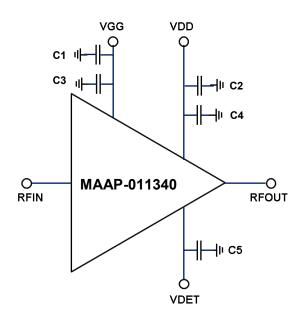
MACOM does not recommend sustained operation near these survivability limits.

<sup>8.</sup> Junction temperature directly effects device MTTF. Junction temperature should be kept as low as possible to maximize lifetime.



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## **Application Schematic**



#### **Parts List**

Part #	Value	Case Style	
C1, C2	10 μF	1210	
C3, C4	1000 pF	0402	
C5	1 μF	0402	
J1, J2	100-mil pitch double row DC header		
J3 - J6	Southwest 2.4 mm, 5 mil pin diameter		

#### Recommended PCB Information

RF input and output are 50  $\Omega$  transmission lines on single layer 7.3 mil Rogers RO4350B LoPro with 1.5 oz. Cu. For best thermal management, use as many copper filled vias under the device as physically possible. The filled vias should be plated over. 8 mil diameter vias in a 5 x 5 array are used on this sample board.

## **PCB Layout Stack-Up**

BOARD DIELECTRIC / COPPER STACKUP
FINISHED BOARD THICKNESS
(EXCLUDING PRIMARY SOLDERMASK)

PRIMARY SOLDERMASK (POSITIVE IMAGE)

1 oz Cu. PLATING (PRIMARY LAYER)

11.5 +/- 10%

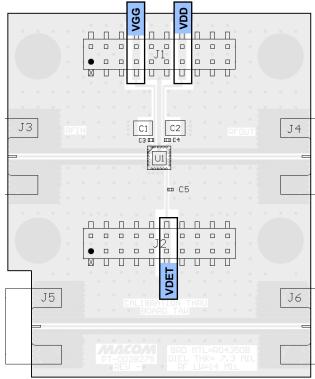
R04350B LoPro FOIL (PRIMARY LAYER)

1 oz Cu. LoPro FOIL (SECONDARY LAYER)

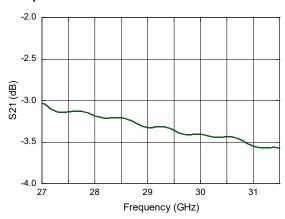
1 oz Cu. PLATING (SECONDARY LAYER)

Finished board thickness is in mils

## **Sample Board Layout**



#### Sample Board Thru Line Loss

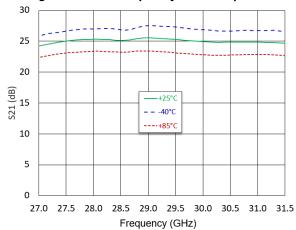




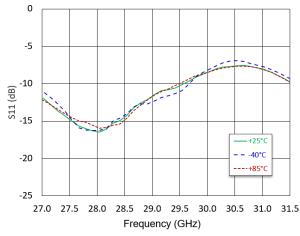
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## **Typical Performance Curves:**

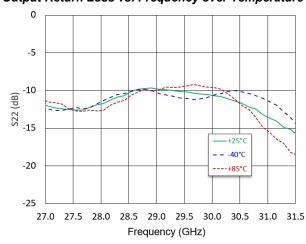
#### Small Signal Gain vs. Frequency over Temperature



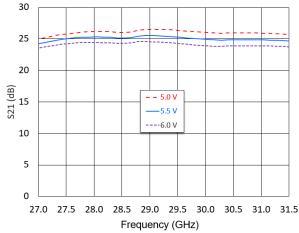
#### Input Return Loss vs. Frequency over Temperature



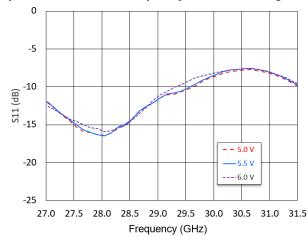
#### Output Return Loss vs. Frequency over Temperature



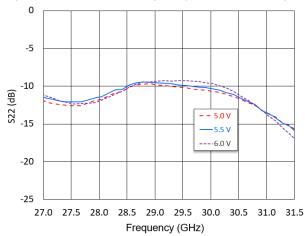
#### Small Signal Gain vs. Frequency over Bias Voltage



#### Input Return Loss vs. Frequency over Bias Voltage



#### Output Return Loss vs. Frequency over Bias Voltage

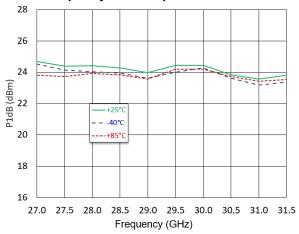




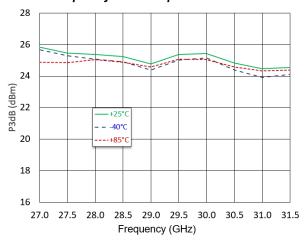
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## **Typical Performance Curves:**

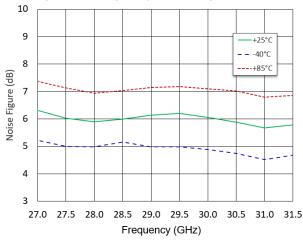
#### P1dB vs. Frequency over Temperature



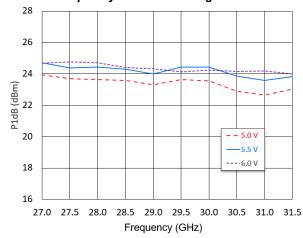
#### P3dB vs. Frequency over Temperature



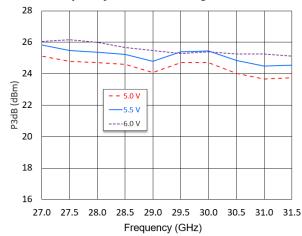
#### Noise Figure vs. Frequency over Temperature



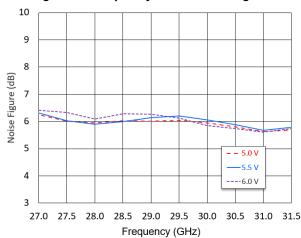
#### P1dB vs. Frequency over Bias Voltage



#### P3dB vs. Frequency over Bias Voltage



#### Noise Figure vs. Frequency over Bias Voltage

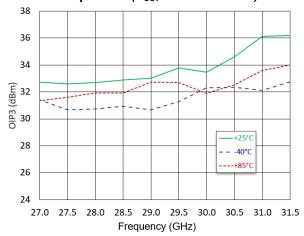




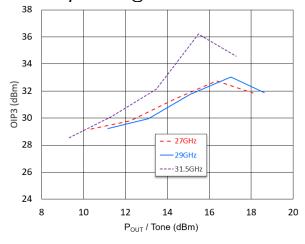
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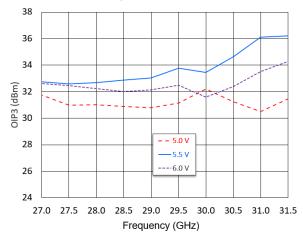
#### OIP3 over Temperature (Pout = 16 dBm / Tone)



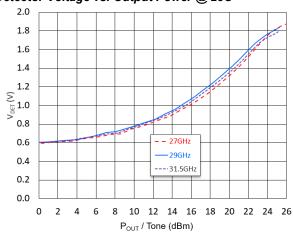
#### OIP3 vs. Output Power @ 25C



#### OIP3 over Bias Voltage (P<sub>OUT</sub> = 16 dBm / Tone)



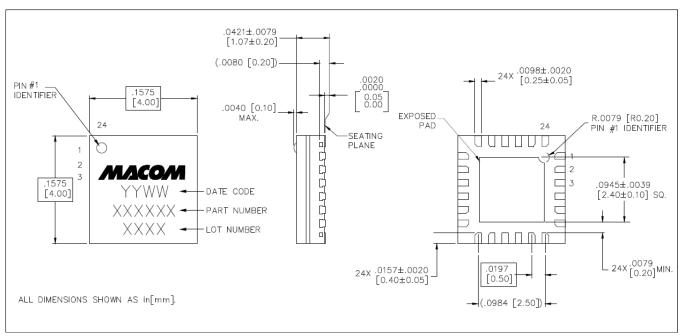
#### Detector Voltage vs. Output Power @ 25C





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## Lead-Free 4 mm 24-Lead AQFN Package<sup>†</sup>



<sup>†</sup> Reference Application Note S2083 for lead-free solder reflow recommendations. Meets JEDEC moisture sensitivity level 3 requirements. Plating is NiPdAu

# 0.25 W Ka-Band Amplifier 27 - 31.5 GHz



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